SEMI M23.4-0211 (Reapproved 0218)
SPECIFICATION FOR ROUND 100 mm POLISHED MONOCRYSTALLINE INDIUM PHOSPHIDE WAFERS FOR ELECTRONIC AND OPTOELECTRONIC DEVICE APPLICATIONS (DOVE-TAIL TYPE)

This Standard was technically approved by the Compound Semiconductor Materials Global Technical Committee. This edition was approved for publication by the global Audits and Reviews Subcommittee on June 28, 2017. Available at www.semiviews.org and www.semi.org in February 2018; originally published September 1999; previously published February 2011.

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1 Purpose

1.1 This Specification defines properties of round 100 mm monocrystalline indium phosphide wafers, in agreement with presently established industry practice. It uniquely defines those mechanical parameters that do not need, for technical reasons, a choice of different values.

2 Scope

2.1 The parameters defined include the values and tolerances of wafer diameter, thickness and surface orientation.

2.2 The complete specification for this product includes all general requirements of SEMI M23, excluding those that are not relevant to this Specification.

NOTICE: SEMI Standards and Safety Guidelines do not purport to address all safety issues associated with their use. It is the responsibility of the users of the Documents to establish appropriate safety and health practices, and determine the applicability of regulatory or other limitations prior to use.

3 Referenced Standards and Documents

3.1 *SEMI Standards and Safety Guidelines*

SEMI M23 — Specification for Polished Monocrystalline Indium Phosphide Wafers

NOTICE: Unless otherwise indicated, all documents cited shall be the latest published versions.

Table 1 Dimension and Tolerance Requirements

Property	*Dimension*	*Tolerance*	*Units*
Diameter[#1]	100.0	±0.5	mm
Thickness, Center Point	625.0	±25	µm
Primary Flat Length	32.5	±2	mm
Secondary Flat Length	18.0	±2	mm

#1 The diameter standard means that the dimension is centered to this value.

Table 2 Orientation and Flat Location Requirements

Property	*Requirement*
Option	Dove-Tail
Primary Flat Orientation	$(0\bar{1}\bar{1})$ ± 0.5 (see SEMI M23, Figure 1) under an indium facet. The primary flat shall be perpendicular to the 'Dove-Tail' etch figure.[#1]
Secondary Flat Orientation	$(0\bar{1}1)$ 90° ± 5° clockwise from the primary flat.
Surface Orientation	
A.	(100) ± 0.5° (see SEMI M23, Figure 1)

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Property	*Requirement*
B.	(100) off 2° ± 0.5° toward the $(1\bar{1}0)$ plane[#2] (see SEMI M23, Figure 2)
Orthogonal Misorientation	±5° (see SEMI M23, Figure 3)

#1 Since there are various etchants, the appropriate etching method for revealing etch pits can be determined by each manufacturer. For example, see ¶ 13.1 of SEMI M23: "HBr-$K_2Cr_2O_7$-H_2O etching system for indium phosphide."

#2 The frame of reference is the (100) plane of the crystal. It is the wafer normal that is tilted toward the $(1\bar{1}0)$ plane of the crystal.

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